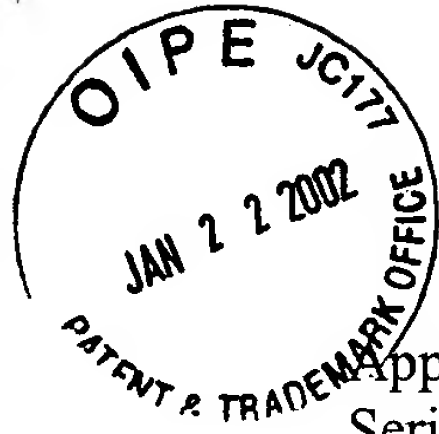


Receipt *[Signature]*



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Shunpei YAMAZAKI et al.      Art Unit : 2812  
Serial No. : 09/769,765      Examiner : Unknown  
Filed : January 26, 2001  
Title : SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

Commissioner for Patents  
Washington, D.C. 20231

**SECOND REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT**

Please correct the Filing Receipt for the above-referenced application to identify the proper priority date and to include the residence addresses for the inventors, *i.e.*, Shunpei Yamazaki, Tokyo, Japan and Jun Koyama, Kanagawa, Japan.

Please supply a corrected Filing Receipt to the undersigned with respect to this application. A copy of the original Filing Receipt showing the desired changes in red ink and a copy of the Combined Declaration and Power of Attorney are attached for your convenience.

No fee is believed to be due. If, however, there are any charges or credits, please apply them to Deposit Account No. 06-1050.

Respectfully submitted,

Date: January 22, 2002

*[Signature]*  
\_\_\_\_\_  
John F. Hayden  
Reg. No. 37,640

Fish & Richardson P.C.  
601 Thirteenth Street, NW  
Washington, DC 20005  
Telephone: (202) 783-5070  
Facsimile: (202) 783-2331

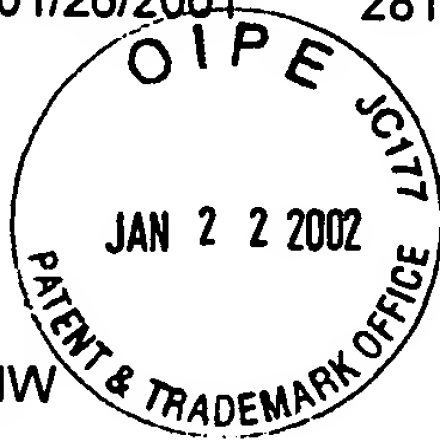


## UNITED STATES PATENT AND TRADEMARK OFFICE

COMMISSIONER FOR PATENTS  
UNITED STATES PATENT AND TRADEMARK OFFICE  
WASHINGTON, D.C. 20231  
www.uspto.gov

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/769,765	01/26/2001	2812	<del>0.00</del> 1886	12732-008001	16	47	10

JOHN F. HAYDEN  
Fish & Richardson P.C.  
601 Thirteenth Street, NW  
Washington, DC 20005



CONFIRMATION NO. 7392

CORRECTED FILING RECEIPT



\*OC000000006029904\*

Date Mailed: 05/02/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

## Applicant(s)

Shunpei Yamazaki, Residence Not Provided;  
Jun Koyama, Residence Not Provided;

Tokyo, Japan  
Kanagawa, Japan

Domestic Priority data as claimed by applicant

## Foreign Applications

JAPAN 2000-018097 01/26/2001

2000

If Required, Foreign Filing License Granted 05/01/2001

Projected Publication Date: To Be Determined - pending completion of Missing Parts

Non-Publication Request: No

Early Publication Request: No

## Title

Semiconductor device and manufacturing method thereof

Preliminary Class

RECEIVED  
APR 10 2001  
HIGH SPEED DIVISION